

## ABSTRACT

In order to obtain a thin plate manufacturing method capable of extremely increasing manufacturing efficiency by enlarging the production scale and remarkably reducing the manufacturing cost per unit area and an apparatus for manufacturing this  
5 thin plate, a method and an apparatus performing introduction of a substrate into a main chamber and discharge of the substrate from the main chamber through at least one subsidiary chamber (3, 4) adjacent to the main chamber (1) are employed when manufacturing a silicon thin plate by dipping a surface layer part of the substrate into a  
10 silicon melt (7) in a crucible (2) arranged in the main chamber (1) for bonding silicon (5) to the surface of the substrate.